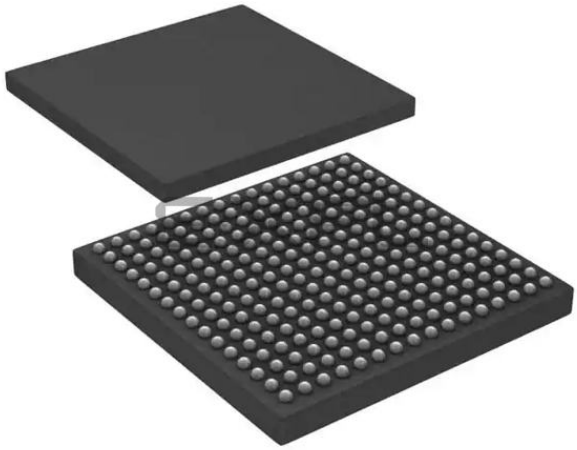

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4/M0
Core Size	32-Bit Dual-Core
Speed	204MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I²C, IrDA, Microwire, QEI, SD, SPI, SSI, SSP, UART/USART, USB, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, LCD, Motor Control PWM, POR, PWM, WDT
Number of I/O	164
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	16K x 8
RAM Size	136K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 3.6V
Data Converters	A/D 8x10b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	256-LBGA
Supplier Device Package	256-LBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc4353jet256-551

- Cortex-M0 Processor core
  - ARM Cortex-M0 co-processor (version r0p0) capable of off-loading the main ARM Cortex-M4 application processor.
  - Running at frequencies of up to 204 MHz.
  - JTAG
  - Built-in NVIC.
- On-chip memory
  - Up to 1 MB on-chip dual bank flash memory with flash accelerator.
  - 16 kB on-chip EEPROM data memory.
  - 136 kB SRAM for code and data use.
  - Multiple SRAM blocks with separate bus access. Two SRAM blocks can be powered down individually.
  - 64 kB ROM containing boot code and on-chip software drivers.
  - 64 bit+ 256 bit of One-Time Programmable (OTP) memory for general-purpose use.
- Configurable digital peripherals
  - Serial GPIO (SGPIO) interface.
  - State Configurable Timer (SCTimer/PWM) subsystem on AHB.
  - Global Input Multiplexer Array (GIMA) allows to cross-connect multiple inputs and outputs to event driven peripherals like the timers, SCTimer/PWM, and ADC0/1.
- Serial interfaces
  - Quad SPI Flash Interface (SPIFI) with four lanes and up to 52 MB per second.
  - 10/100T Ethernet MAC with RMII and MII interfaces and DMA support for high throughput at low CPU load. Support for IEEE 1588 time stamping/advanced time stamping (IEEE 1588-2008 v2).
  - One High-speed USB 2.0 Host/Device/OTG interface with DMA support and on-chip high-speed PHY.
  - One High-speed USB 2.0 Host/Device interface with DMA support, on-chip full-speed PHY and ULPI interface to external high-speed PHY.
  - USB interface electrical test software included in ROM USB stack.
  - One 550 UART with DMA support and full modem interface.
  - Three 550 USARTs with DMA and synchronous mode support and a smart card interface conforming to ISO7816 specification. One USART with IrDA interface.
  - Up to two C_CAN 2.0B controllers with one channel each.
  - Two SSP controllers with FIFO and multi-protocol support. Both SSPs with DMA support.
  - One SPI controller.
  - One Fast-mode Plus I^2C-bus interface with monitor mode and with open-drain I/O pins conforming to the full I^2C-bus specification. Supports data rates of up to 1 Mbit/s.
  - One standard I^2C-bus interface with monitor mode and with standard I/O pins.
  - Two I^2S interfaces, each with DMA support and with one input and one output.
- Digital peripherals
  - External Memory Controller (EMC) supporting external SRAM, ROM, NOR flash, and SDRAM devices.

- LCD controller with DMA support and a programmable display resolution of up to 1024 H × 768 V. Supports monochrome and color STN panels and TFT color panels; supports 1/2/4/8 bpp Color Look-Up Table (CLUT) and 16/24-bit direct pixel mapping. Available on parts LPC4357/53 only.
- Secure Digital Input Output (SD/MMC) card interface.
- Eight-channel General-Purpose DMA controller can access all memories on the AHB and all DMA-capable AHB slaves.
- Up to 164 General-Purpose Input/Output (GPIO) pins with configurable pull-up/pull-down resistors.
- GPIO registers are located on the AHB for fast access. GPIO ports have DMA support.
- Up to eight GPIO pins can be selected from all GPIO pins as edge and level sensitive interrupt sources.
- Two GPIO group interrupt modules enable an interrupt based on a programmable pattern of input states of a group of GPIO pins.
- Four general-purpose timer/counters with capture and match capabilities.
- One motor control Pulse Width Modulator (PWM) for three-phase motor control.
- One Quadrature Encoder Interface (QEI).
- Repetitive Interrupt timer (RI timer).
- Windowed watchdog timer (WWDT).
- Ultra-low power Real-Time Clock (RTC) on separate power domain with 256 bytes of battery powered backup registers.
- Alarm timer; can be battery powered.

- Analog peripherals
  - One 10-bit DAC with DMA support and a data conversion rate of 400 kSamples/s.
  - Two 10-bit ADCs with DMA support and a data conversion rate of 400 kSamples/s. Up to eight input channels per ADC.
- Unique ID for each device.
- Clock generation unit
  - Crystal oscillator with an operating range of 1 MHz to 25 MHz.
  - 12 MHz internal RC oscillator trimmed to 3 % accuracy over temperature and voltage (1.5 % accuracy for T_{amb} = 0 °C to 85 °C).
  - Ultra-low power Real-Time Clock (RTC) crystal oscillator.
  - Three PLLs allow CPU operation up to the maximum CPU rate without the need for a high-frequency crystal. The second PLL can be used with the High-speed USB, the third PLL can be used as audio PLL.
  - Clock output.
- Power
  - Single 3.3 V (2.4 V to 3.6 V) power supply with on-chip DC-to-DC converter for the core supply and the RTC power domain.
  - RTC power domain can be powered separately by a 3 V battery supply.
  - Four reduced power modes: Sleep, Deep-sleep, Power-down, and Deep power-down.
  - Processor wake-up from Sleep mode via wake-up interrupts from various peripherals.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
P1_8	R7	H5	71	51	[2]	N; PU	I/O	**GPIO1[1] —** General purpose digital input/output pin.
							O	**U1_DTR —** Data Terminal Ready output for UART1.
							O	**CTOUT_12 —** SCT output 12. Match output 3 of timer 3.
							I/O	**EMC_D1 —** External memory data line 1.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**SD_VOLT0 —** SD/MMC bus voltage select output 0.
P1_9	T7	J5	73	52	[2]	N; PU	I/O	**GPIO1[2] —** General purpose digital input/output pin.
							O	**U1_RTS —** Request to Send output for UART1.
							O	**CTOUT_11 —** SCT output 11. Match output 3 of timer 2.
							I/O	**EMC_D2 —** External memory data line 2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**SD_DAT0 —** SD/MMC data bus line 0.
P1_10	R8	H6	75	53	[2]	N; PU	I/O	**GPIO1[3] —** General purpose digital input/output pin.
							I	**U1_RI —** Ring Indicator input for UART1.
							O	**CTOUT_14 —** SCT output 14. Match output 2 of timer 3.
							I/O	**EMC_D3 —** External memory data line 3.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**SD_DAT1 —** SD/MMC data bus line 1.
P1_11	T9	J7	77	55	[2]	N; PU	I/O	**GPIO1[4] —** General purpose digital input/output pin.
							I	**U1_CTS —** Clear to Send input for UART1.
							O	**CTOUT_15 —** SCT output 15. Match output 3 of timer 3.
							I/O	**EMC_D4 —** External memory data line 4.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**SD_DAT2 —** SD/MMC data bus line 2.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
P4_0	D5	-	1	1	[2]	N; PU	I/O	**GPIO2[0] —** General purpose digital input/output pin.
							O	**MCOA0 —** Motor control PWM channel 0, output A.
							I	**NMI —** External interrupt input to NMI.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**LCD_VD13 —** LCD data.
							I/O	**U3_UCLK —** Serial clock input/output for USART3 in synchronous mode.
							-	**R —** Function reserved.
P4_1	A1	-	3	3	[5]	N; PU	I/O	**GPIO2[1] —** General purpose digital input/output pin.
							O	**CTOUT_1 —** SCT output 1. Match output 3 of timer 3.
							O	**LCD_VD0 —** LCD data.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**LCD_VD19 —** LCD data.
							O	**U3_TXD —** Transmitter output for USART3.
							I	**ENET_COL —** Ethernet Collision detect (MII interface).
							AI	**ADC0_1 —** ADC0 and ADC1, input channel 1. Configure the pin as GPIO input and use the ADC function select register in the SCU to select the ADC.
P4_2	D3	-	12	8	[2]	N; PU	I/O	**GPIO2[2] —** General purpose digital input/output pin.
							O	**CTOUT_0 —** SCT output 0. Match output 0 of timer 0.
							O	**LCD_VD3 —** LCD data.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**LCD_VD12 —** LCD data.
							I	**U3_RXD —** Receiver input for USART3.
							I/O	**SGPIO8 —** General purpose digital input/output pin.
P4_3	C2	-	10	7	[5]	N; PU	I/O	**GPIO2[3] —** General purpose digital input/output pin.
							O	**CTOUT_3 —** SCT output 3. Match output 3 of timer 0.
							O	**LCD_VD2 —** LCD data.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**LCD_VD21 —** LCD data.
							I/O	**U3_BAUD —** Baud pin for USART3.
							I/O	**SGPIO9 —** General purpose digital input/output pin.
							AI	**ADC0_0 —** DAC, ADC0 and ADC1, input channel 0. Configure the pin as GPIO input and use the ADC function select register in the SCU to select the ADC.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
P8_2	K4	-	36	-	[3]	N; PU	I/O	**GPIO4[2] —** General purpose digital input/output pin.
							O	**USB0_IND0 —** USB0 port indicator LED control output 0.
							-	**R —** Function reserved.
							I	**MCI0 —** Motor control PWM channel 0, input.
							I/O	**SGPIO10 —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**T0_MAT2 —** Match output 2 of timer 0.
P8_3	J3	-	37	-	[2]	N; PU	I/O	**GPIO4[3] —** General purpose digital input/output pin.
							I/O	**USB1_ULPI_D2 —** ULPI link bidirectional data line 2.
							-	**R —** Function reserved.
							O	**LCD_VD12 —** LCD data.
							O	**LCD_VD19 —** LCD data.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**T0_MAT3 —** Match output 3 of timer 0.
P8_4	J2	-	39	-	[2]	N; PU	I/O	**GPIO4[4] —** General purpose digital input/output pin.
							I/O	**USB1_ULPI_D1 —** ULPI link bidirectional data line 1.
							-	**R —** Function reserved.
							O	**LCD_VD7 —** LCD data.
							O	**LCD_VD16 —** LCD data.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I	**T0_CAP0 —** Capture input 0 of timer 0.
P8_5	J1	-	40	-	[2]	N; PU	I/O	**GPIO4[5] —** General purpose digital input/output pin.
							I/O	**USB1_ULPI_D0 —** ULPI link bidirectional data line 0.
							-	**R —** Function reserved.
							O	**LCD_VD6 —** LCD data.
							O	**LCD_VD8 —** LCD data.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I	**T0_CAP1 —** Capture input 1 of timer 0.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
PA_2	K15	-	136	-	[3]	N; PU	I/O	**GPIO4[9] —** General purpose digital input/output pin.
							I	**QEI_PHB —** Quadrature Encoder Interface PHB input.
							-	**R —** Function reserved.
							I	**U2_RXD —** Receiver input for USART2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PA_3	H11	-	147	-	[3]	N; PU	I/O	**GPIO4[10] —** General purpose digital input/output pin.
							I	**QEI_PHA —** Quadrature Encoder Interface PHA input.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PA_4	G13	-	151	-	[2]	N; PU	-	**R —** Function reserved.
							O	**CTOUT_9 —** SCT output 9. Match output 3 of timer 3.
							-	**R —** Function reserved.
							I/O	**EMC_A23 —** External memory address line 23.
							I/O	**GPIO5[19] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PB_0	B15	-	164	-	[2]	N; PU	-	**R —** Function reserved.
							O	**CTOUT_10 —** SCT output 10. Match output 3 of timer 3.
							O	**LCD_VD23 —** LCD data.
							-	**R —** Function reserved.
							I/O	**GPIO5[20] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
PC_2	F6	-	13	-	[2]	N; PU	I/O	**USB1_ULPI_D6 —** ULPI link bidirectional data line 6.
							-	**R —** Function reserved.
							I	**U1_CTS —** Clear to Send input for UART 1.
							O	**ENET_TXD2 —** Ethernet transmit data 2 (MII interface).
							I/O	**GPIO6[1] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**SD_RST —** SD/MMC reset signal for MMC4.4 card.
PC_3	F5	-	11	-	[5]	N; PU	I/O	**USB1_ULPI_D5 —** ULPI link bidirectional data line 5.
							-	**R —** Function reserved.
							O	**U1_RTS —** Request to Send output for UART 1. Can also be configured to be an RS-485/EIA-485 output enable signal for UART 1.
							O	**ENET_TXD3 —** Ethernet transmit data 3 (MII interface).
							I/O	**GPIO6[2] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**SD_VOLT1 —** SD/MMC bus voltage select output 1.
							AI	**ADC1_0 —** DAC, ADC1 and ADC0, input channel 0. Configure the pin as GPIO input and use the ADC function select register in the SCU to select the ADC.
PC_4	F4	-	16	-	[2]	N; PU	-	**R —** Function reserved.
							I/O	**USB1_ULPI_D4 —** ULPI link bidirectional data line 4.
							-	**R —** Function reserved.
								ENET_TX_EN — Ethernet transmit enable (RMII/MII interface).
							I/O	**GPIO6[3] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							I	**T3_CAP1 —** Capture input 1 of timer 3.
							I/O	**SD_DAT0 —** SD/MMC data bus line 0.
PC_5	G4	-	20	-	[2]	N; PU	-	**R —** Function reserved.
							I/O	**USB1_ULPI_D3 —** ULPI link bidirectional data line 3.
							-	**R —** Function reserved.
							O	**ENET_TX_ER —** Ethernet Transmit Error (MII interface).
							I/O	**GPIO6[4] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							I	**T3_CAP2 —** Capture input 2 of timer 3.
							I/O	**SD_DAT1 —** SD/MMC data bus line 1.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP208	LQFP144		Reset state [1]	Type	Description
PC_14	N1	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							-	**R —** Function reserved.
							I	**U1_RXD —** Receiver input for UART 1.
							-	**R —** Function reserved.
							I/O	**GPIO6[13] —** General purpose digital input/output pin.
							I/O	**SGPIO13 —** General purpose digital input/output pin.
							O	**ENET_TX_ER —** Ethernet Transmit Error (MII interface).
							I/O	**SD_DAT7 —** SD/MMC data bus line 7.
PD_0	N2	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							O	**CTOUT_15 —** SCT output 15. Match output 3 of timer 3.
							O	**EMC_DQMOUT2 —** Data mask 2 used with SDRAM and static devices.
							-	**R —** Function reserved.
							I/O	**GPIO6[14] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**SGPIO4 —** General purpose digital input/output pin.
PD_1	P1	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**EMC_CKEOUT2 —** SDRAM clock enable 2.
							-	**R —** Function reserved.
							I/O	**GPIO6[15] —** General purpose digital input/output pin.
							O	**SD_POW —** SD/MMC power monitor output.
							-	**R —** Function reserved.
							I/O	**SGPIO5 —** General purpose digital input/output pin.
PD_2	R1	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							O	**CTOUT_7 —** SCT output 7. Match output 3 of timer 1.
							I/O	**EMC_D16 —** External memory data line 16.
							-	**R —** Function reserved.
							I/O	**GPIO6[16] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**SGPIO6 —** General purpose digital input/output pin.

7.6.1 Features

- ARM Cortex-M4 core:
  - Controls system exceptions and peripheral interrupts
  - Support for up to 53 vectored interrupts
  - Eight programmable interrupt priority levels with hardware priority level masking
  - Relocatable vector table
  - Non-Maskable Interrupt (NMI)
  - Software interrupt generation
- ARM Cortex-M0 core:
  - Support for up to 32 interrupts
  - Four programmable interrupt priority levels with hardware priority level masking

7.6.2 Interrupt sources

Each peripheral device has one interrupt line connected to the NVIC but may have several interrupt flags. Individual interrupt flags may also represent more than one interrupt source.

7.7 System Tick timer (SysTick)

The ARM Cortex-M4 includes a system tick timer (SYSTICK) that is intended to generate a dedicated SYSTICK exception at a 10 ms interval.

Remark: The SysTick is not included in the ARM Cortex-M0 core implementation.

7.8 Event router

The event router combines various internal signals, interrupts, and the external interrupt pins (WAKEUP[3:0]) to create an interrupt in the NVIC, if enabled. In addition, the event router creates a wake-up signal to the ARM core and the CCU for waking up from Sleep, Deep-sleep, Power-down, and Deep power-down modes. Individual events can be configured as edge or level sensitive and can be enabled or disabled in the event router. The event router can be battery powered.

The following events if enabled in the event router can create a wake-up signal from sleep, deep-sleep, power-down, and deep power-down modes and/or create an interrupt:

- External pins WAKEUP0/1/2/3 and $\overline{\text{RESET}}$
- Alarm timer, RTC (32 kHz oscillator running)

The following events if enabled in the event router can create a wake-up signal from sleep mode only and/or create an interrupt:

- WWDT, BOD interrupts.
- C_CAN0/1 and QEI interrupts.
- Ethernet, USB0, USB1 signals.
- Selected outputs of combined timers (SCTimer/PWM and timer0/1/3).

After a few commands configure the interface at startup, the entire flash content is accessible as normal memory using byte, halfword, and word accesses by the processor and/or DMA channels. Simple sequences of commands handle erasing and programming.

Many serial flash devices use a half-duplex command-driven SPI protocol for device setup and initialization and then move to a half-duplex, command-driven 4-bit protocol for normal operation. Different serial flash vendors and devices accept or require different commands and command formats. SPIFI provides sufficient flexibility to be compatible with common flash devices and includes extensions to help insure compatibility with future devices.

7.18.2.1 Features

- Interfaces to serial flash memory in the main memory map.
- Supports classic and 4-bit bidirectional serial protocols.
- Half-duplex protocol compatible with various vendors and devices.
- Quad SPI Flash Interface (SPIFI) with 1-, 2-, or 4-bit data at rates of up to 52 MB per second.
- Supports DMA access.

7.18.3 SD/MMC card interface

The SD/MMC card interface supports the following modes to control:

- Secure Digital memory (SD version 3.0)
- Secure Digital I/O (SDIO version 2.0)
- Consumer Electronics Advanced Transport Architecture (CE-ATA version 1.1)
- MultiMedia Cards (MMC version 4.4)

7.18.4 External Memory Controller (EMC)

Remark: The EMC is available on all LPC435x/3x/2x/1x parts. The following memory bus widths are supported:

- LBGA256 packages: 32 bit
- TFBGA100 packages: 16 bit
- LQFP208 packages: 16 bit
- LQFP144 packages: 16 bit

The LPC435x/3x/2x/1x EMC is a Memory Controller peripheral offering support for asynchronous static memory devices such as RAM, ROM, and NOR flash. In addition, it can be used as an interface with off-chip memory-mapped devices and peripherals.

Table 6. EMC pinout for different packages

Function	LBGA256	TFBGA100	LQFP208	LQFP144
A	EMC_A[23:0]	EMC_A[13:0]	EMC_A[23:0]	EMC_A[15:0]
D	EMC_D[31:0]	EMC_D[7:0]	EMC_D[15:0]	EMC_D[15:0]
$\overline{\text{BLS}}$	$\overline{\text{EMC\_BLS[3:0]}}$	$\overline{\text{EMC\_BLS0}}$	$\overline{\text{EMC\_BLS[1:0]}}$	$\overline{\text{EMC\_BLS[1:0]}}$
$\overline{\text{CS}}$	$\overline{\text{EMC\_CS[3:0]}}$	$\overline{\text{EMC\_CS0}}$	$\overline{\text{EMC\_CS[3:0]}}$	$\overline{\text{EMC\_CS[1:0]}}$

7.23.7 System PLL1

The PLL1 accepts an input clock frequency from an external oscillator in the range of 1 MHz to 25 MHz. The input frequency is multiplied up to a high frequency with a Current Controlled Oscillator (CCO). The multiplier can be an integer value from 1 to 32. The CCO operates in the range of 156 MHz to 320 MHz. This range is possible through an additional divider in the loop to keep the CCO within its frequency range while the PLL is providing the desired output frequency. The output divider can be set to divide by 2, 4, 8, or 16 to produce the output clock. Since the minimum output divider value is 2, it is insured that the PLL output has a 50 % duty cycle. The PLL is turned off and bypassed following a chip reset. After reset, software can enable the PLL. The program must configure and activate the PLL, wait for the PLL to lock, and then connect to the PLL as a clock source. The PLL settling time is 100 μs.

7.23.8 Reset Generation Unit (RGU)

The RGU allows generation of independent reset signals for individual blocks and peripherals on the LPC435x/3x/2x/1x.

7.23.9 Power Management Controller (PMC)

The PMC controls the power to the cores, peripherals, and memories.

The LPC435x/3x/2x/1x support the following power modes in order from highest to lowest power consumption:

1. Active mode
2. Sleep mode
3. Power-down modes:
   a. Deep-sleep mode
   b. Power-down mode
   c. Deep power-down mode

Active mode and sleep mode apply to the state of the core. In a dual-core system, either core can be in active or sleep mode independently of the other core.

If the core is in Active mode, it is fully operational and can access peripherals and memories as configured by software. If the core is in Sleep mode, it receives no clocks, but peripherals and memories remain running.

Either core can enter sleep mode from active mode independently of the other core and while the other core remains in active mode or is in sleep mode.

Power-down modes apply to the entire system. In the Power-down modes, both cores and all peripherals except for peripherals in the always-on power domain are shut down. Memories can remain powered for retaining memory contents as defined by the individual power-down mode.

Either core in active mode can put the part into one of the three power down modes if the core is enabled to do so. If both cores are enabled for putting the system into power-down, then the system enters power-down only once both cores have received a WFI or WFE instruction.

There are three levels of the Code Read Protection:

- In level CRP1, access to the chip via the JTAG is disabled. Partial flash updates are allowed (excluding flash sector 0) using a limited set of the ISP commands. This level is useful when CRP is required and flash field updates are needed. CRP1 does prevent the user code from erasing all sectors.
- In level CRP2, access to the chip via the JTAG is disabled. Only a full flash erase and update using a reduced set of the ISP commands is allowed.
- In level CRP3, any access to the chip via the JTAG pins or the ISP is disabled. This mode also disables the ISP override using P2_7 pin. If necessary, the application code must provide a flash update mechanism using the IAP calls or using the reinvoke ISP command to enable flash update via USART0. See Table 5.

CAUTION

If level three Code Read Protection (CRP3) is selected, no future factory testing can be performed on the device.

7.24 Serial Wire Debug/JTAG

Debug and trace functions are integrated into the ARM Cortex-M4. Serial wire debug and trace functions are supported in addition to a standard JTAG debug and parallel trace functions. The ARM Cortex-M4 is configured to support up to eight breakpoints and four watch points.

Remark: Serial Wire Debug is supported for the ARM Cortex-M4 only,

The ARM Cortex-M0 coprocessor supports JTAG debug. A standard ARM Cortex-compliant debugger can debug the ARM Cortex-M4 and the ARM Cortex-M0 cores separately or both cores simultaneously.

Remark: In order to debug the ARM Cortex-M0, release the M0 reset by software in the RGU block.

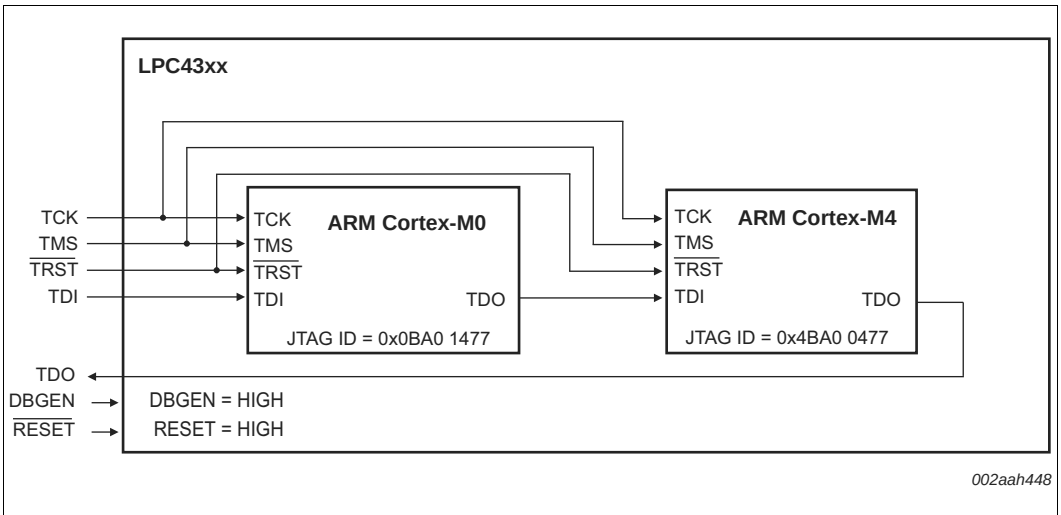


Fig 10. Dual-core debug configuration

Table 11. Static characteristics *…continued*
T_{amb} = −40 °C to +105 °C, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
I_{BAT}	battery supply current	$V_{DD(REG)(3V3)}$ = 3.3 V; V_{BAT} = 3.6 V	[8]				
		deep-sleep mode		-	1.5	-	µA
		power-down mode	[8]	-	1.5	-	µA
		deep power-down mode	[8]	-	1.5	-	µA
I_{BAT}	battery supply current	Deep power-down mode; RTC running; $V_{DD(REG)}$ = VDDA = VDDIO = 0 V; V_{BAT} = 3.3 V		-	3.0	-	µA
		$V_{DD(REG)(3V3)}$ = V_{BAT} = 3.3 V		-	1.5	-	µA
$I_{DD(IO)}$	I/O supply current	deep sleep mode		-	< 0.1	-	µA
		power-down mode		-	< 0.1	-	µA
		deep power-down mode		-	< 0.1	-	µA
I_{DDA}	Analog supply current	on pin VDDA;	[10]	-	0.4	-	
		deep sleep mode					µA
		power-down mode	[10]	-	0.4	-	µA
		deep power-down mode	[10]	-	0.007	-	µA
$\overline{\text{RESET}}$ pin							
V_{IH}	HIGH-level input voltage		[9]	$0.8 \times (V_{ps} - 0.35)$	-	5.5	V
V_{IL}	LOW-level input voltage		[9]	−0.5	-	$0.3 \times (V_{ps} - 0.1)$	V
V_{hys}	hysteresis voltage		[9]	$0.05 \times (V_{ps} - 0.35)$	-	-	V
Standard I/O pins - normal drive strength							
C_I	input capacitance			-	-	2	pF
I_{LL}	LOW-level leakage current	V_I = 0 V; on-chip pull-up resistor disabled		-	3	-	nA
I_{LH}	HIGH-level leakage current	$V_I = V_{DD(IO)}$; on-chip pull-down resistor disabled		-	3	-	nA
		V_I = 5 V; T_{amb} = 25 °C		-	0.5	-	nA
		V_I = 5 V; T_{amb} = 105 °C		-	40	-	nA
I_{OZ}	OFF-state output current	V_O = 0 V to $V_{DD(IO)}$; on-chip pull-up/down resistors disabled; absolute value		-	3	-	nA
V_I	input voltage	pin configured to provide a digital function;		0	-	5.5	V
		$V_{DD(IO)} \geq$ 2.4 V					
		$V_{DD(IO)}$ = 0 V		0	-	3.6	V

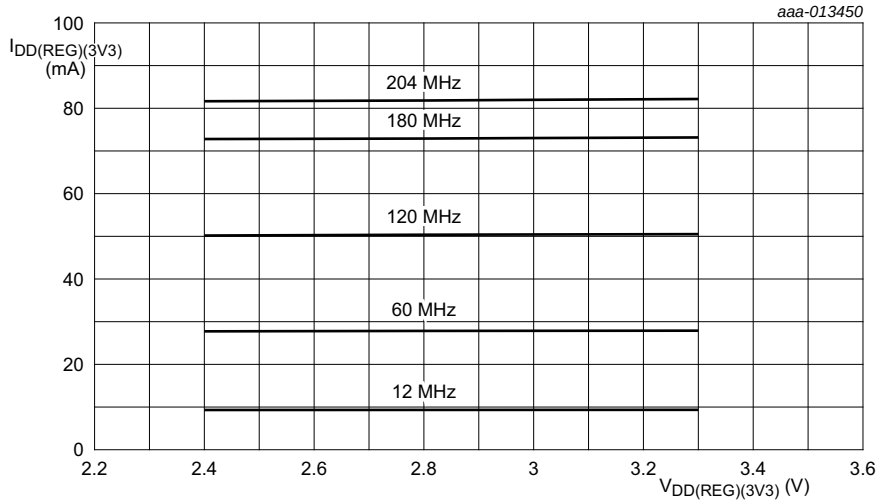
[16] The parameter value specified is a simulated value excluding bond capacitance.

[17] For USB operation 3.0 V ≤ $V_{DD((IO)}$ ≤ 3.6 V. Guaranteed by design.

[18] $V_{DD(IO)}$ present.

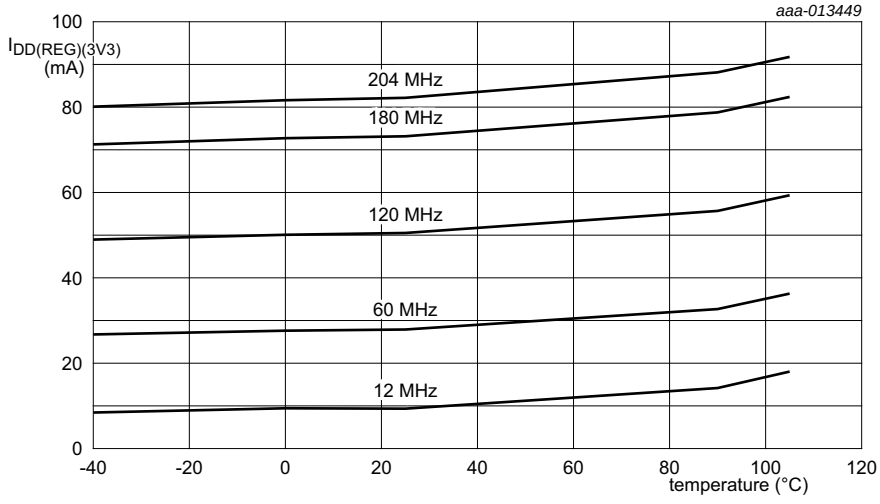
[19] Includes external resistors of 33 Ω ± 1 % on D+ and D−.

10.1 Power consumption



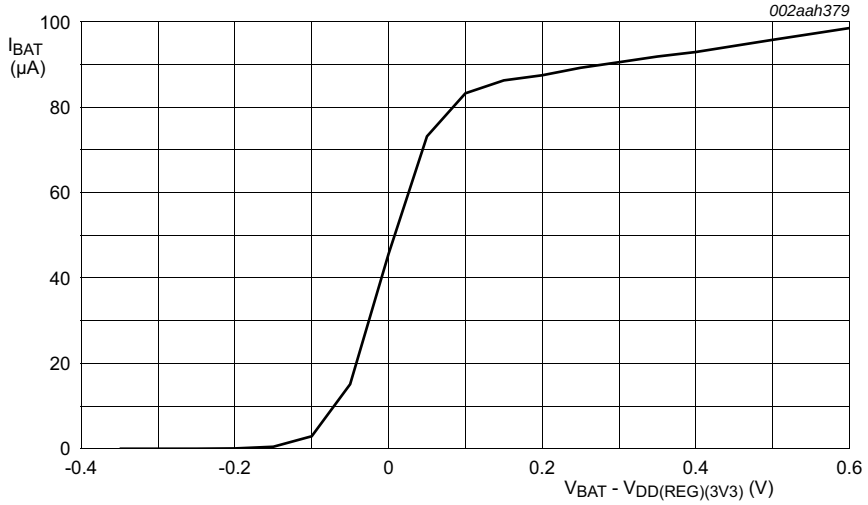
Conditions: T_{amb} = 25 °C; executing code while (1){} from SRAM; M0 core in reset; system PLL enabled; IRC enabled; all peripherals disabled; all peripheral clocks disabled.

Fig 11. Typical supply current versus regulator supply voltage $V_{DD(REEG)(3V3)}$ in active mode



Conditions: $V_{DD(REG)(3V3)}$ = 3.3 V; executing code while (1){} from SRAM; M0 core in reset; system PLL enabled; IRC enabled; all peripherals disabled; all peripheral clocks disabled.

Fig 12. Typical supply current versus temperature in active mode



Conditions: $V_{DD(REG)(3V3)}$ = 3.0 V; V_{BAT} = 2.6 V to 3.6 V; CCLK = 12 MHz.

Remark: The recommended operating condition for the battery supply is $V_{DD(REG)(3V3)} > V_{BAT} + 0.2$ V.

Fig 19. Typical battery supply current in Active mode

10.2 Peripheral power consumption

The typical power consumption at T = 25 °C for each individual peripheral is measured as follows:

1. Enable all branch clocks and measure the current $I_{DD(REG)(3V3)}$.
2. Disable the branch clock to the peripheral to be measured and keep all other branch clocks enabled.
3. Calculate the difference between measurement 1 and 2. The result is the peripheral power consumption.

Table 12. Peripheral power consumption

Peripheral	Branch clock	$I_{DD(REG)(3V3)}$ in mA	
		Branch clock frequency = 48 MHz	Branch clock frequency = 96 MHz
M0 core	CLK_M4_M0APP	3.3	6.6
I2C1	CLK_APB3_I2C1	0.01	0.01
I2C0	CLK_APB1_I2C0	< 0.01	0.02
DAC	CLK_APB3_DAC	0.01	0.02
ADC0	CLK_APB3_ADC0	0.07	0.07
ADC1	CLK_APB3_ADC1	0.07	0.07
CAN0	CLK_APB3_CAN0	0.17	0.17
CAN1	CLK_APB1_CAN1	0.16	0.15
MOTOCON	CLK_APB1_MOTOCON	0.04	0.04
I2S	CLK_APB1_I2S	0.09	0.08
SPIFI	CLK_SPIFI, CLK_M4_SPIFI	1.14	2.29

11.15 SPIFI

Table 29. Dynamic characteristics: SPIFI

T_{amb} = −40 °C to 105 °C; 2.4 V ≤ $V_{DD(REG)(3V3)}$ ≤ 3.6 V; 2.7 V ≤ $V_{DD(IO)}$ ≤ 3.6 V. C_L = 20 pF. Sampled at 90 % and 10 % of the signal level. EHS = 1 for all pins. Simulated values.

Symbol	Parameter	Min	Max	Unit
$T_{cy(clk)}$	clock cycle time	9.6	-	ns
t_{DS}	data set-up time	3.2	-	ns
t_{DH}	data hold time	0	-	ns
$t_{v(Q)}$	data output valid time	-	3.2	ns
$t_{h(Q)}$	data output hold time	0.6	-	ns

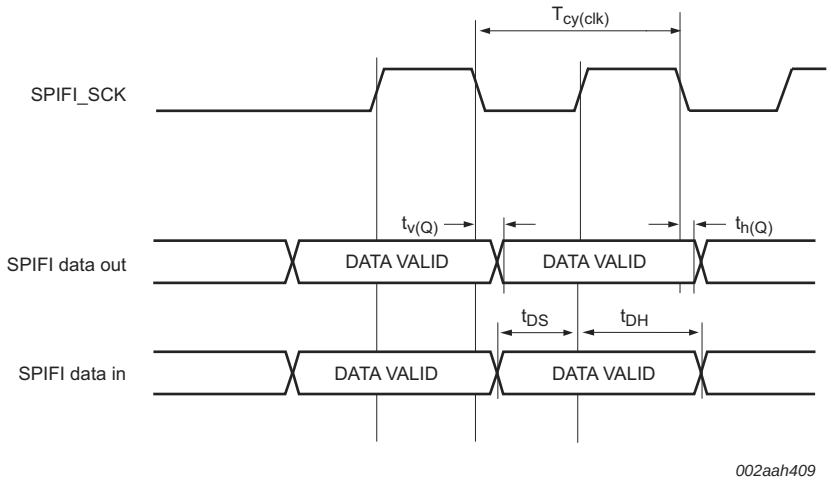
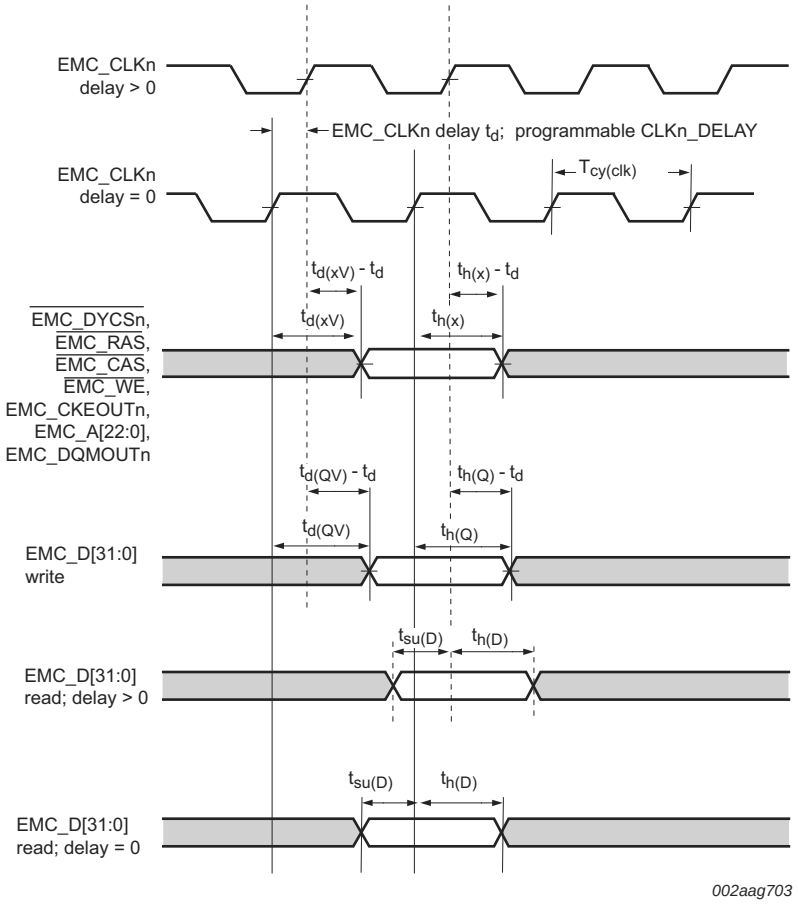


Fig 33. SPIFI timing (Mode 0)

11.16 SGPIO timing

The following considerations apply to SGPIO timing:

- SGPIO input signals are synchronized by the internal clock SGPIO_CLOCK. To guarantee that no samples are missed, all input signals should have a duration of at least one SGPIO_CLOCK cycle plus the set-up and hold times.
- When an external clock input is used to generate output data, synchronization causes a latency of at least one SGPIO_CLOCK cycle. The maximum output data rate is one output every two SGPIO_CLOCK cycles.
- Synchronization also causes a latency of one SGPIO_CLOCK cycle when sampling several inputs. This may cause inputs with very similar timings to be sampled with a difference of one SGPIO_CLOCK cycle.



For the programmable EMC_CLK[3:0] clock delays CLKn_DELAY, see Table 31.

Remark: For SDRAM operation, set CLK0_DELAY = CLK1_DELAY = CLK2_DELAY = CLK3_DELAY in the EMCDELAYCLK register.

Fig 37. SDRAM timing

13.3 RTC oscillator

In the RTC oscillator circuit, only the crystal (XTAL) and the capacitances C_{RTCX1} and C_{RTCX2} need to be connected externally. Typical capacitance values for C_{RTCX1} and C_{RTCX2} are $C_{RTCX1/2}$ = 20 (typical) $\pm$ 4 pF.

An external clock can be connected to RTCX1 if RTCX2 is left open. The recommended amplitude of the clock signal is $V_{i(RMS)}$ = 100 mV to 200 mV with a coupling capacitance of 5 pF to 10 pF.

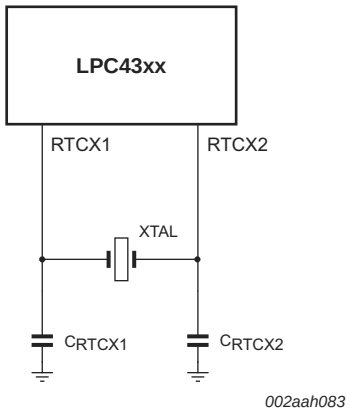


Fig 45. RTC 32 kHz oscillator circuit

13.4 XTAL and RTCX Printed Circuit Board (PCB) layout guidelines

Connect the crystal on the PCB as close as possible to the oscillator input and output pins of the chip. Take care that the load capacitors C_{X1}, C_{X2}, and C_{X3} in case of third overtone crystal usage have a common ground plane. Also connect the external components to the ground plain. To keep the noise coupled in via the PCB as small as possible, make loops and parasitics as small as possible. Choose smaller values of C_{X1} and C_{X2} if parasitics increase in the PCB layout.

Ensure that no high-speed or high-drive signals are near the RTCX1/2 signals.

13.5 Standard I/O pin configuration

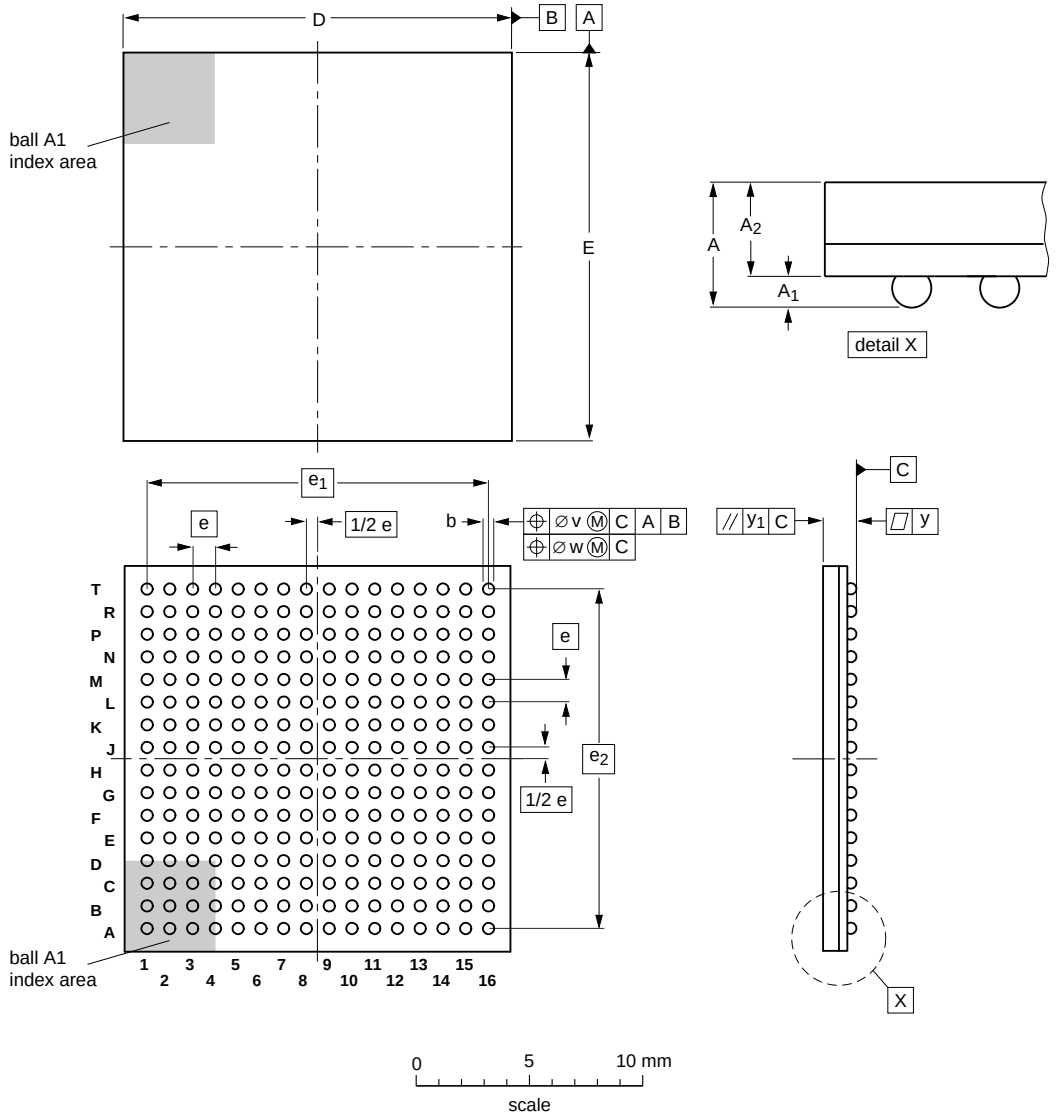
Figure 46 shows the possible pin modes for standard I/O pins with analog input function:

- Digital output driver enabled/disabled
- Digital input: Pull-up enabled/disabled
- Digital input: Pull-down enabled/disabled
- Digital input: Repeater mode enabled/disabled
- Digital input: Input buffer enabled/disabled
- Analog input

The default configuration for standard I/O pins is input buffer disabled and pull-up enabled. The weak MOS devices provide a drive capability equivalent to pull-up and pull-down resistors.

14. Package outline

LBGA256: plastic low profile ball grid array package; 256 balls; body 17 x 17 x 1 mm **SOT740-2**



DIMENSIONS (mm are the original dimensions)

UNIT	A max	A_1	A_2	b	D	E	e	e_1	e_2	v	w	y	y_1
mm	1.55	0.45 0.35	1.1 0.9	0.55 0.45	17.2 16.8	17.2 16.8	1	15	15	0.25	0.1	0.12	0.35

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT740-2	- - -	MO-192	- - -			~~05-06-16~~ 05-08-04

Fig 51. Package outline LBGA256 package

18. Revision history

Table 47. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
LPC435X_3X_2X_1X v.5.3	20160315	Product data sheet	-	LPC435X_3X_2X_1X v.5.2
	• Updated Table 32 “Dynamic characteristics: Dynamic external memory interface”: Read cycle parameters $t_{h(D)}$ min value is 2.2 ns and max value is “-”.			
LPC435X_3X_2X_1X v.5.2	20151126	Product data sheet		LPC435X_3X_2X_1X v.5.1
Modifications:	• Fixed cross references in Table 3 “Pin description”.			
LPC435X_3X_2X_1X v.5.1	20151116	Product data sheet	2015110041	LPC435X_3X_2X_1X v.5
Modifications:	• Updated Table 2 “Ordering options”. TFBGA100 packages do not support ULPI interface. • Changed the EMC on TFBGA100 packages from 8 bit to 16 bit. See Section 7.18.4 “External Memory Controller (EMC)” • Fixed the sentence: the voltage divider should provide a reduction of 3.6 V/5.25 V or ~0.686 V to read the voltage divider should provide a reduction of 3.6 V/5.25 V or ~0.686 in Section 13.5.2 “Suggested USB interface solutions” on page 141. • Changed footnote 12 in Table 3 “Pin description” with the text: VPP is internally connected to VDDIO for all packages with the exception of the LFBGA256 package. • Updated the features of the SSP functional description: Maximum SSP speed in full-duplex mode of 25.5 Mbit/s; for transmit only 51 Mbit/s (master) and 11 Mbit/s (slave), see Section 7.19.4.1 “Features”. • Updated SSP slave and SSP master values in Table 27 “Dynamic characteristics: SSP pins in SPI mode”. Updated footnote 2 to: $T_{cy(clk)} \geq 12 \times T_{cy(PCLK)}$. – removed $t_{v(Q)}$, data output valid time in SPI mode, minimum value of 3 ´ (1/PCLK) from SSP slave mode. – added units to t_d, delay time, for SSP slave and master mode. • Updated Figure 29 “I2S-bus timing (receive)”. • Added GPCLKIN section and table. See Section 11.7 “GPCLKIN” and Table 22 “Dynamic characteristic: GPCLKIN”. • Updated Table 11 “Static characteristics”. I_{BAT} in deep power-down mode; RTC running; $V_{DD(REG)}$ = VDDA = VDDIO = 0 V; Was: $V_{DD(REG)(3V3)}$ floating.			
LPC435X_3X_2X_1X v.5	20150428	Product data sheet	201408004F01	LPC435X_3X_2X_1X v.4